

L Number	Hits	Search Text	DB	Time stamp
1	3251	((438/704,706,709,710,711,719,745,753)).CCL	USPAT; US-PGFUB; EPO; JPO; DEPVENT; IBM_TIB	2002/06/12 13:16
2	16	((438/704,706,709,710,711,719,745,753)).CCL and (wet adj etching).ti.	USPAT; US-PGFUB; EPO; JPO; DEPVENT; IBM_TIB	2002/06/12 13:16
3	5	((438/704,706,709,710,711,719,745,753)).CCL and (wet adj etching).ti.) and plasma	USPAT; US-PGFUB; EPO; JPO; DEPVENT; IBM_TIB	2002/06/12 13:18
4	5	((438/704,706,709,710,711,719,745,753)).CCL and (wet adj etching).ti.) and plasma and wet near3 etching	USPAT; US-PGFUB; EPO; JPO; DEPVENT; IBM_TIB	2002/06/12 13:21
5	2	((438/704,706,709,710,711,719,745,753)).CCL and wet adj etching with substrate with plasma adj etching	USPAT; US-PGFUB; EPO; JPO; DEPVENT; IBM_TIB	2002/06/12 13:25
6	32	((438/704,706,709,710,711,719,745,753)).CCL and alignment adj mark	USPAT; US-PGFUB; EPO; JPO; DEPVENT; IBM_TIB	2002/06/12 13:25
7	31	((438/704,706,709,710,711,719,745,753)).CCL and plasma adj etching with wet adj etching	USPAT; US-PGFUB; EPO; JPO; DEPVENT; IBM_TIB	2002/06/12 13:42
8	25	((438/704,706,709,710,711,719,745,753)).CCL and wet adj etching with advantages	USPAT; US-PGFUB; EPO; JPO; DEPVENT; IBM_TIB	2002/06/12 13:44
9	13	((438/704,706,709,710,711,719,745,753)).CCL and fine with wet adj etching	USPAT; US-PGFUB; EPO; JPO; DEPVENT; IBM_TIB	2002/06/12 13:55
10	132	((438/704,706,709,710,711,719,745,753)).CCL and wet adj etching and cost	USPAT; US-PGFUB; EPO; JPO; DEPVENT; IBM_TIB	2002/06/12 13:55
11	14	((438/704,706,709,710,711,719,745,753)).CCL and wet adj etching and cost and wet adj etching with plasma	USPAT; US-PGFUB; EPO; JPO; DEPVENT; IBM_TIB	2002/06/12 14:36
12	2	jp-62018714-\$.did.	USPAT; US-PGFUB; EPO; JPO; DEPVENT; IBM_TIB	2002/06/12 14:36